

# Radiation Hardness Studies in a CCD with High-Speed Column Parallel Readout

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On behalf of the LCFI Collaboration

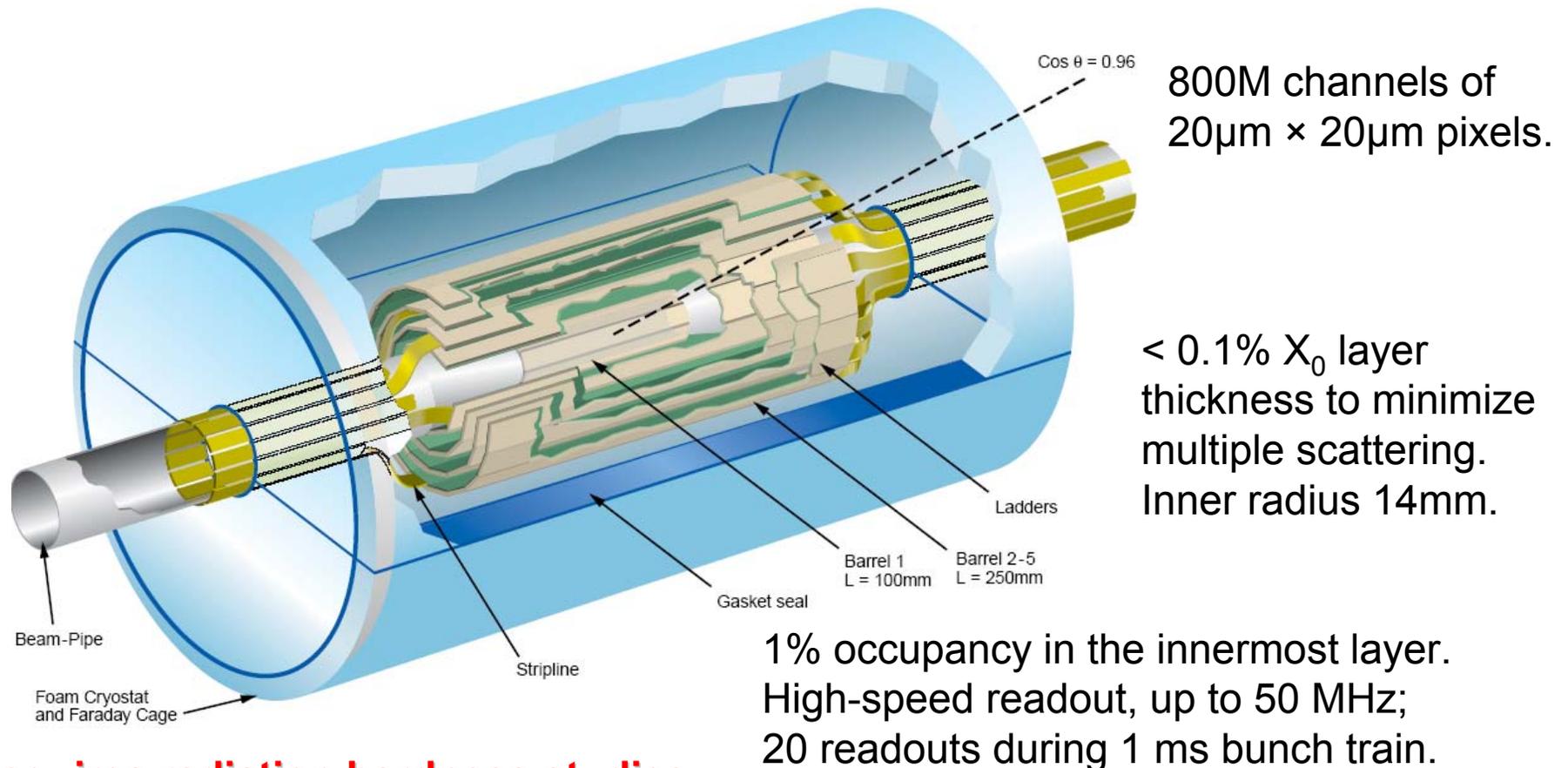
# Outline

- ILC and CCD Vertex Detector
- Background rates and radiation damage
- Charge Transfer Inefficiency (CTI)
- TCAD simulation results
- Comparison with an analytical model
- Test-stand measurements in preparation
- Conclusions

# International Linear Collider: Vertex Detector

LCFI: Linear Collider Flavour Identification collaboration

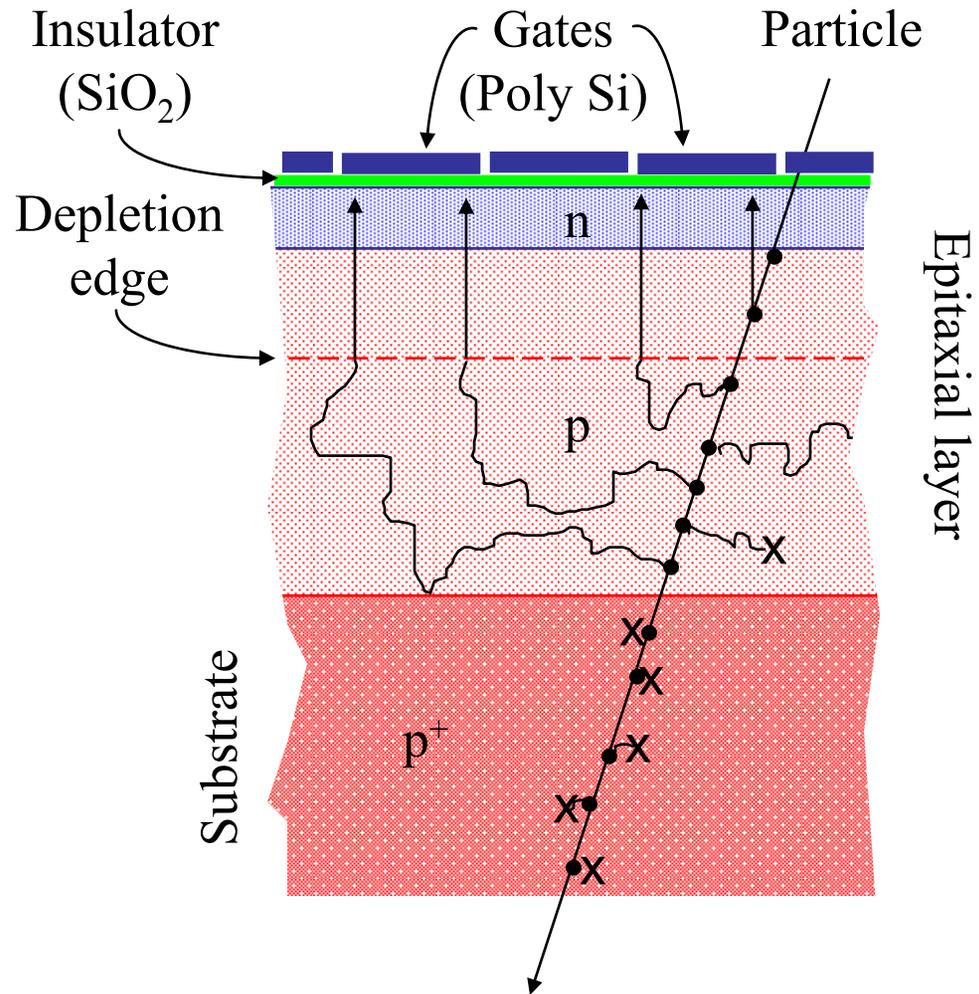
**Vertex Detector will provide precise 3D space points along tracks.**



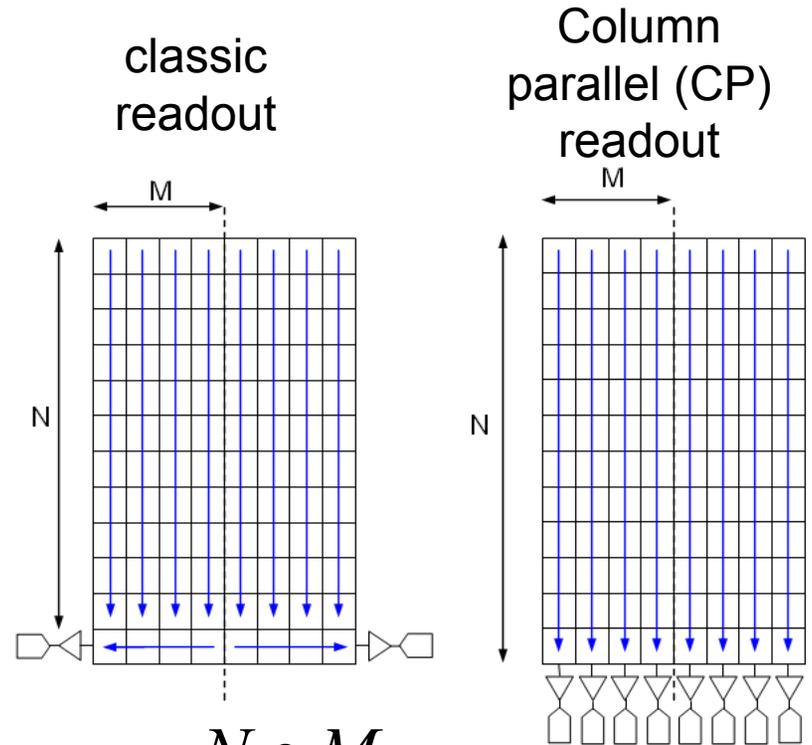
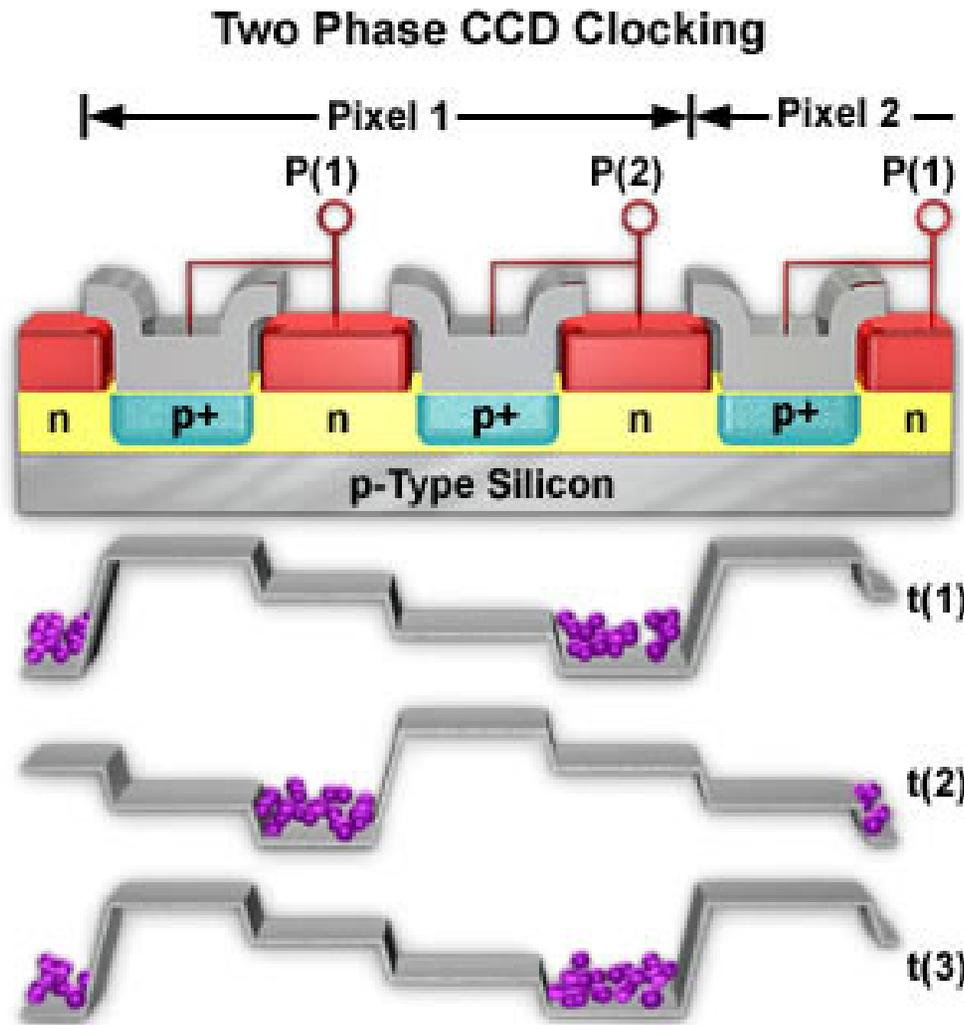
**Requires radiation hardness studies.**

A. Sopczak, ALCPG'07, 25-10-07

# The CCD: Charge Collection



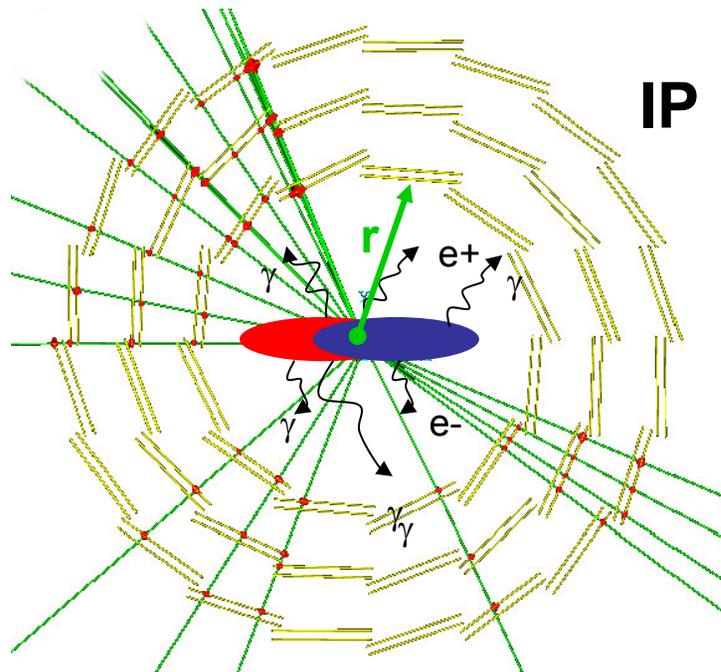
# The CCD: Charge Transfer



$$t_{serial} = \frac{N \cdot M}{f_{out}}$$

$$t_{CP-CCD} = \frac{N}{f_{out}}$$

# ILC Background and CCD Radiation Damage

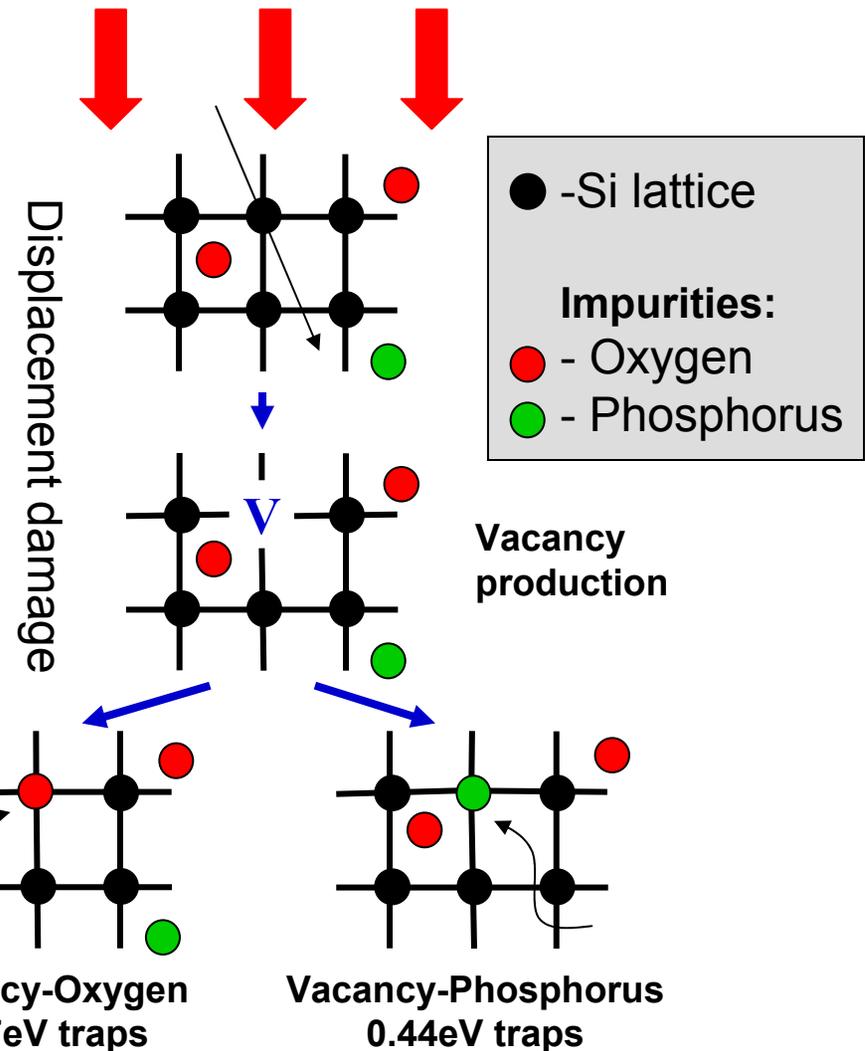


Background: e and n (from  $\gamma$  reactions)

Radiation damage produces energy levels (**traps**) within the band gap.

**Traps** capture electrons from the conduction band which are later released.

Background particles



A. Sopczak, ALCPG'07, 25-10-07

# Estimation of Background Rates

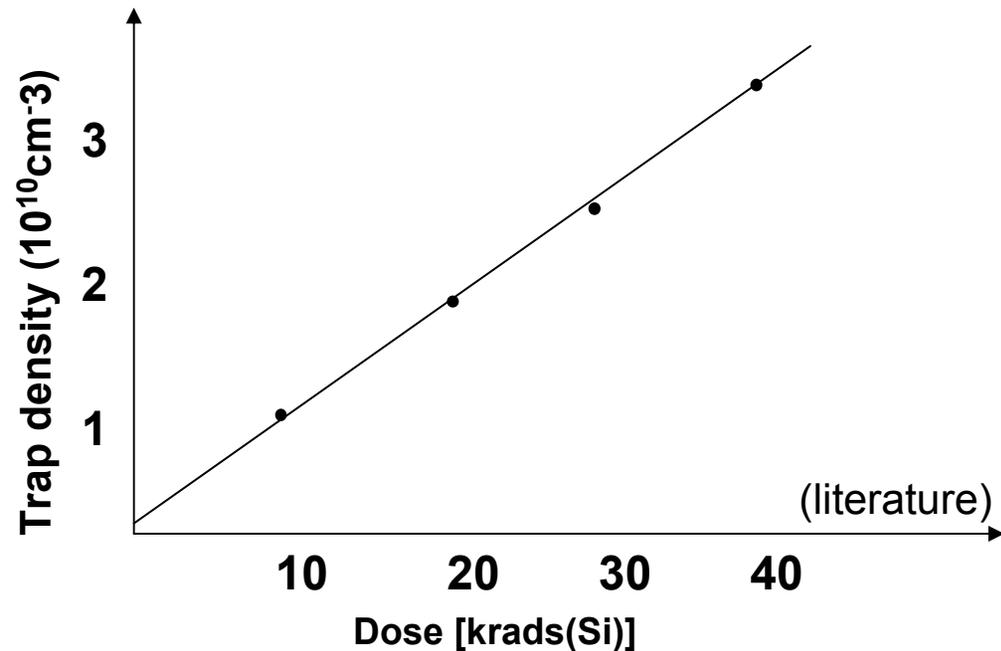
Simulator (e <sup>+</sup> e <sup>-</sup> pairs)	SiD	LDC	GLD
<b>CAIN/Jupiter</b> hits/cm <sup>2</sup> /bx	<b>2.9</b> (nominal)	<b>3.5</b> (TESLA)	<b>0.5</b> (24mm radius, nominal)
<b>GuineaPig</b> hits/cm <sup>2</sup> /bx	<b>2.3</b> (nominal)	<b>3.0</b> (TESLA)	<b>2.0</b> (20mm radius, nominal)

(bx: bunch crossing)

(T.Maruyama, C.Rimbault)

- 2820 bx/train
- 5 trains per second
- 10<sup>7</sup> seconds in the 'Snowmass year'

**1.41·10<sup>11</sup> bunches/year**



# Background and Trap Density

Expected background in the ILC at 14 mm radius for 1 year operation.

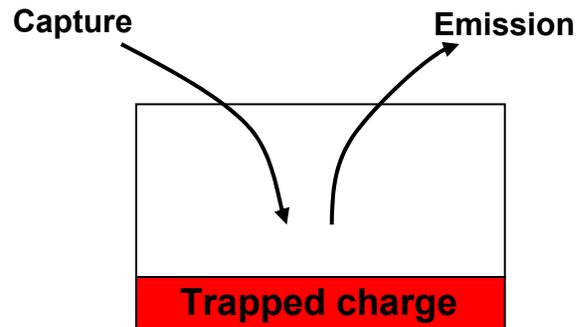
Parameter	electrons	neutrons
average energy	~ 10MeV	~ 1MeV
no. particles / bx / cm <sup>2</sup>	3.5	0.01
fluence (annual dose)	$0.5 \cdot 10^{12}$	$1.6 \cdot 10^9$ Vogel $1 \cdot 10^9$ Maruyama

Estimated trap densities for simulation purpose.

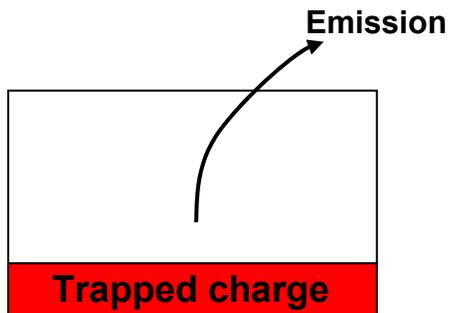
Source	- 0.17eV trap	- 0.44eV trap
electrons	$\sim 3 \cdot 10^{11} \text{ cm}^{-3}$	$\sim 3 \cdot 10^{10} \text{ cm}^{-3}$
neutrons	$\sim 7.1 \cdot 10^8 \text{ cm}^{-3}$ $\sim 4.5 \cdot 10^8 \text{ cm}^{-3}$	$\sim 1.1 \cdot 10^{10} \text{ cm}^{-3}$ $\sim 7.0 \cdot 10^9 \text{ cm}^{-3}$
total	$\sim 3 \cdot 10^{11} \text{ cm}^{-3}$	$\sim 4.1 \cdot 10^{10} \text{ cm}^{-3}$ $\sim 3.7 \cdot 10^{10} \text{ cm}^{-3}$
<b>Used in simulations</b>	$1 \cdot 10^{12} \text{ cm}^{-3}$	$1 \cdot 10^{12} \text{ cm}^{-3}$

Simulation: about 3 or many more years of operation.

# CTI Modeling - Principle



During transfer



After transfer

- Traps capture electrons from the signal charge.
- Electrons are emitted later:  
capture  $\tau_c$  and emission  $\tau_e$  time constants.

$$\tau_c = \frac{1}{\sigma_n v_{th} n_s} \quad (\sim \text{ns})$$

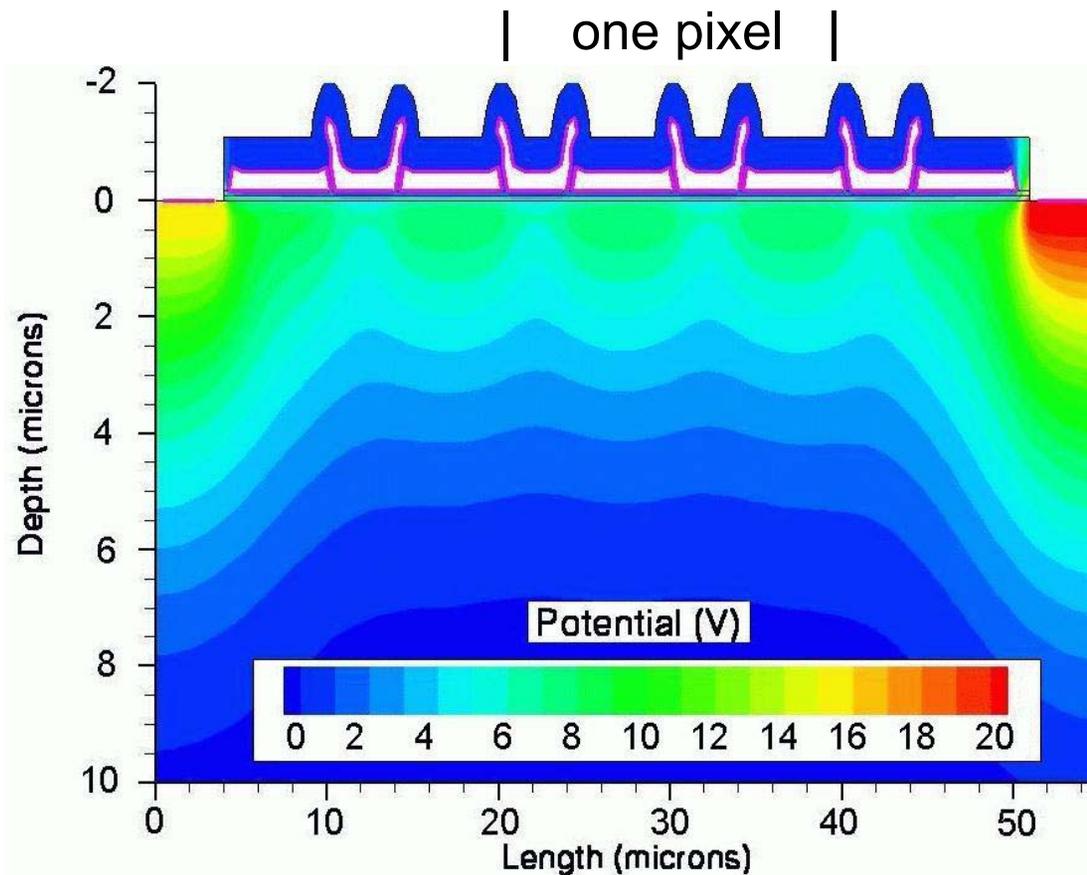
$$\tau_e = \frac{1}{\sigma_n x_n v_{th} N_c} \exp\left(\frac{E_c - E_t}{kT}\right)$$

Strongly dependent on temperature and trap energy level (seconds to ns)

# CCD Simulations in ISE-TCAD

**ISE-TCAD** package (version 7.5) - **DESSIS** program (**D**evice **S**imulation for **S**mart **I**ntegrated **S**ystems).

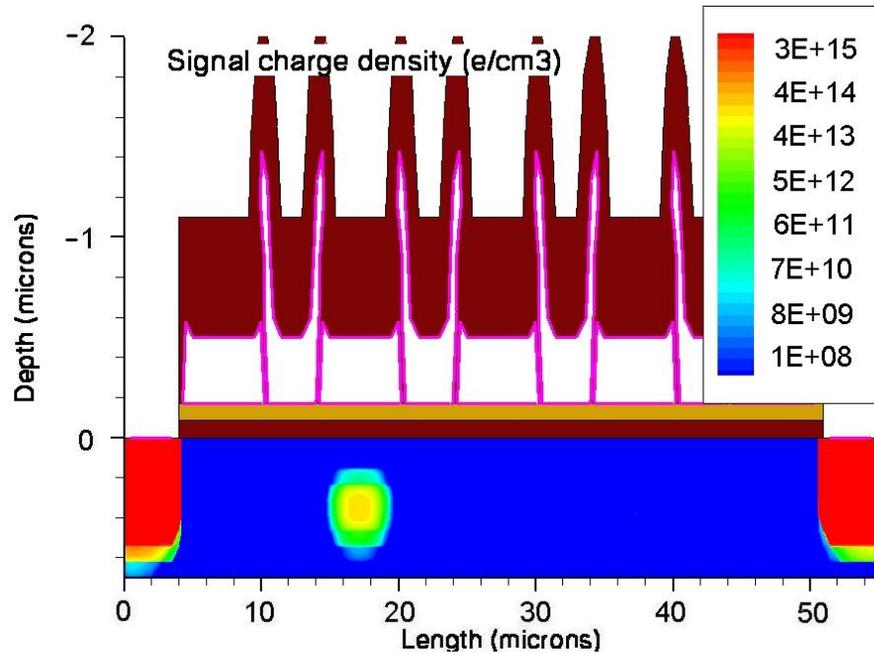
Simplified 2D model containing only one pixel of CCD structure.



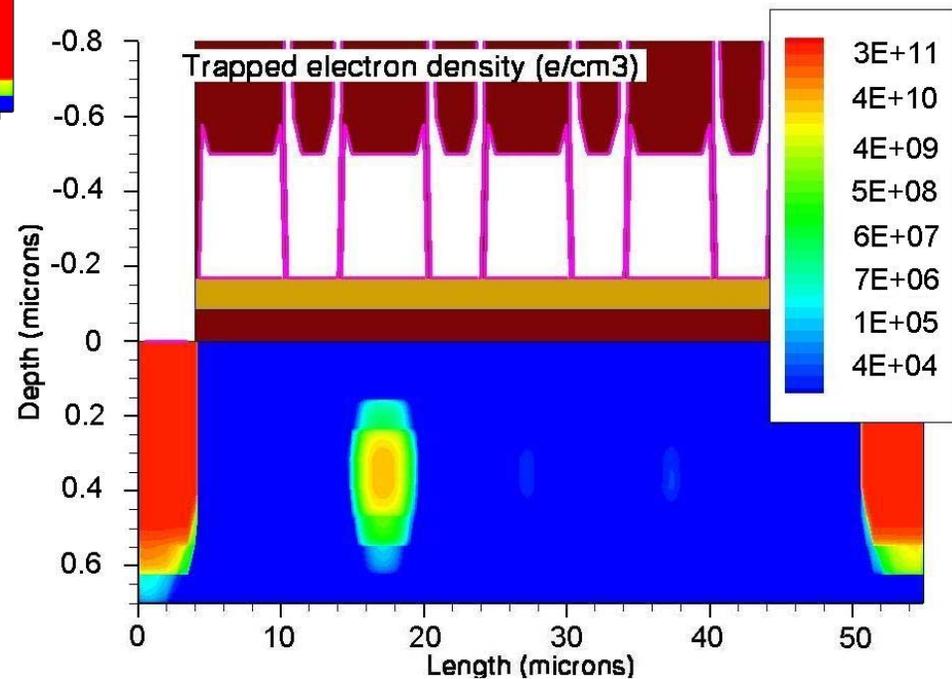
Epitaxial layer is doped with boron (p-type)

additional doping profiles:  
substrate, p+ implants,  
input gate, and output  
gate. The contact nodes  
for the pixels are poly-  
silicon with silicon nitride  
and silicon oxide.  
layers beneath them.

# CTI Definition and Modelling in TCAD



**CTI** – the ratio of the charge lost in the transfer from pixel  $n$  to pixel  $n+1$  to the charge entering pixel  $n$ .



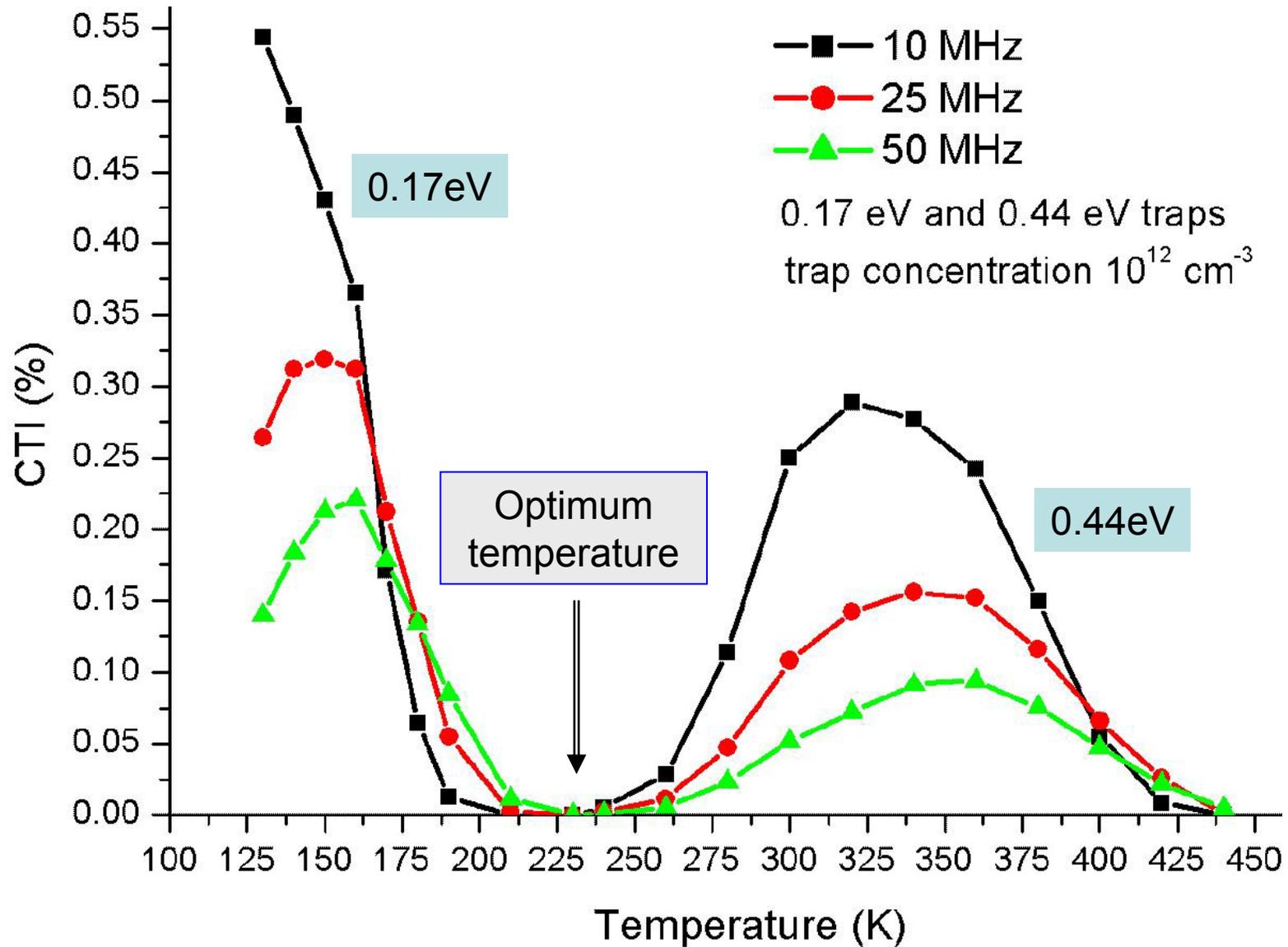
# Simulations

Parameters of CTI simulations:

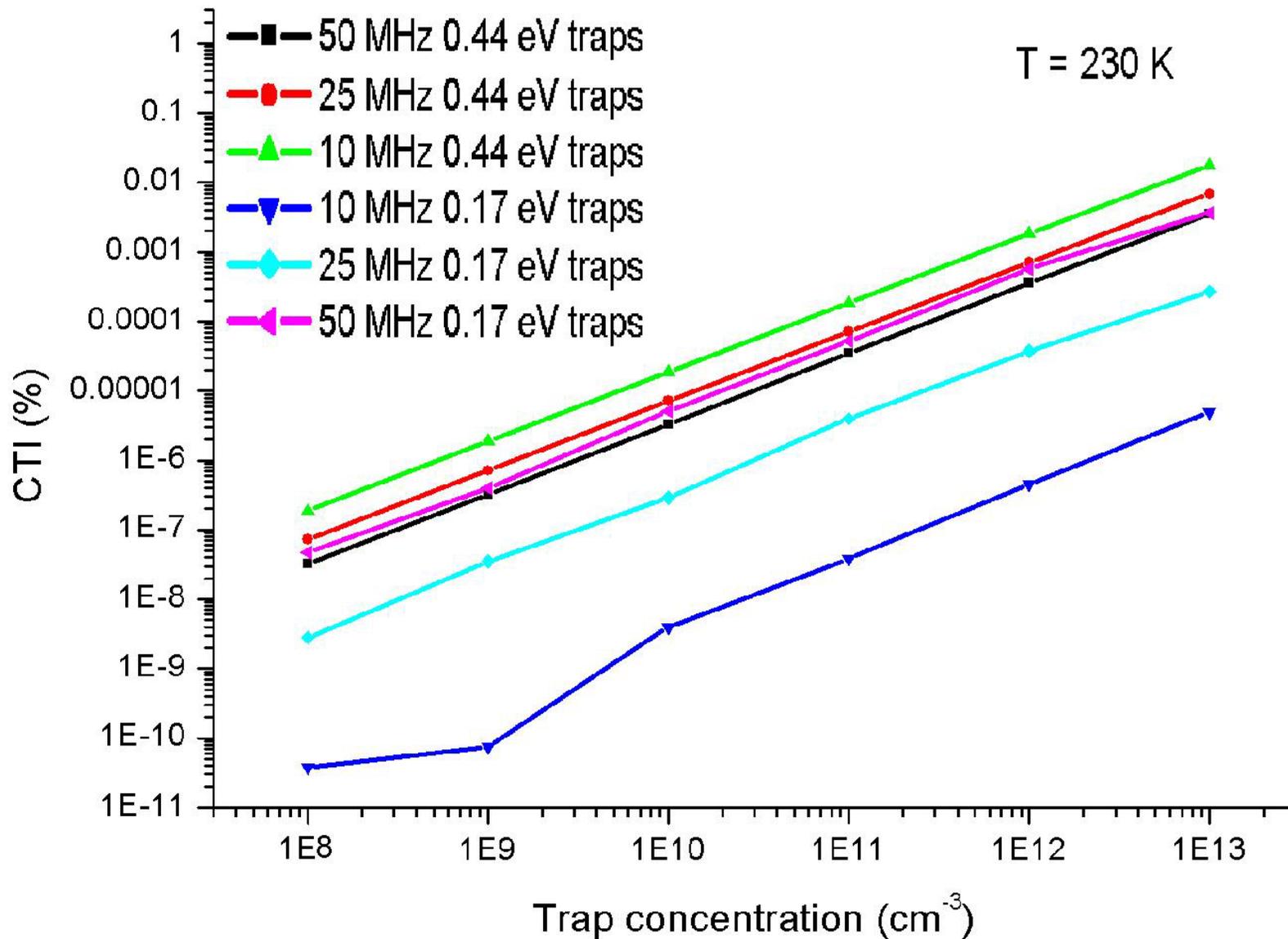
- trap energy levels (0.17 and 0.44 eV)
- clock frequency (10 to 50 MHz)
- temperature (130 to 440 K)
- trap concentration ( $10^8$  to  $10^{13}/\text{cm}^3$ )
- hit (pixel) occupancy (0.1% to 1%)
- trap energy level variation  $0.17 \pm 0.005$  eV

Clock-voltage induced CTI related to power consumption.

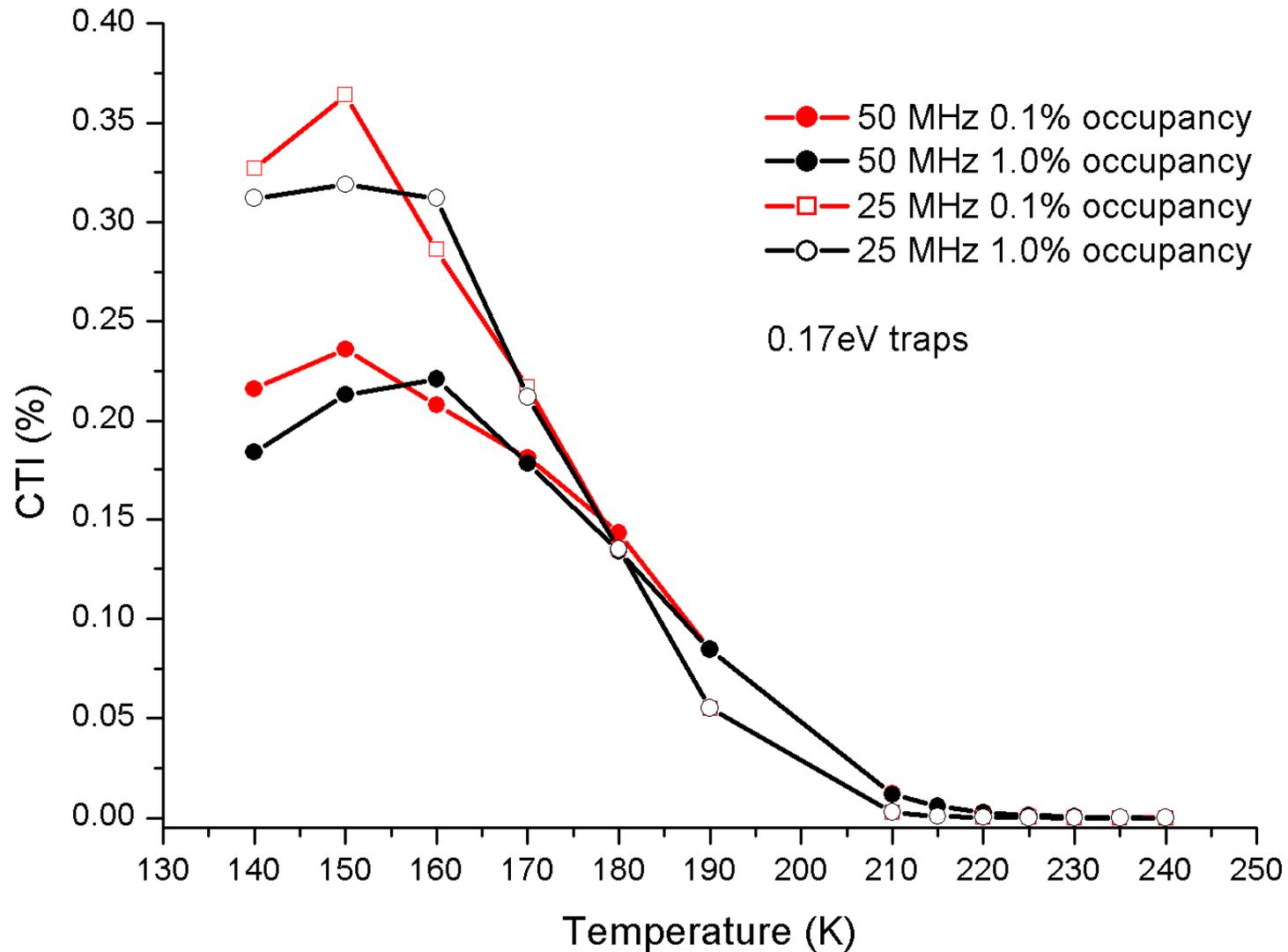
# CTI: Temperatures and Different Frequencies



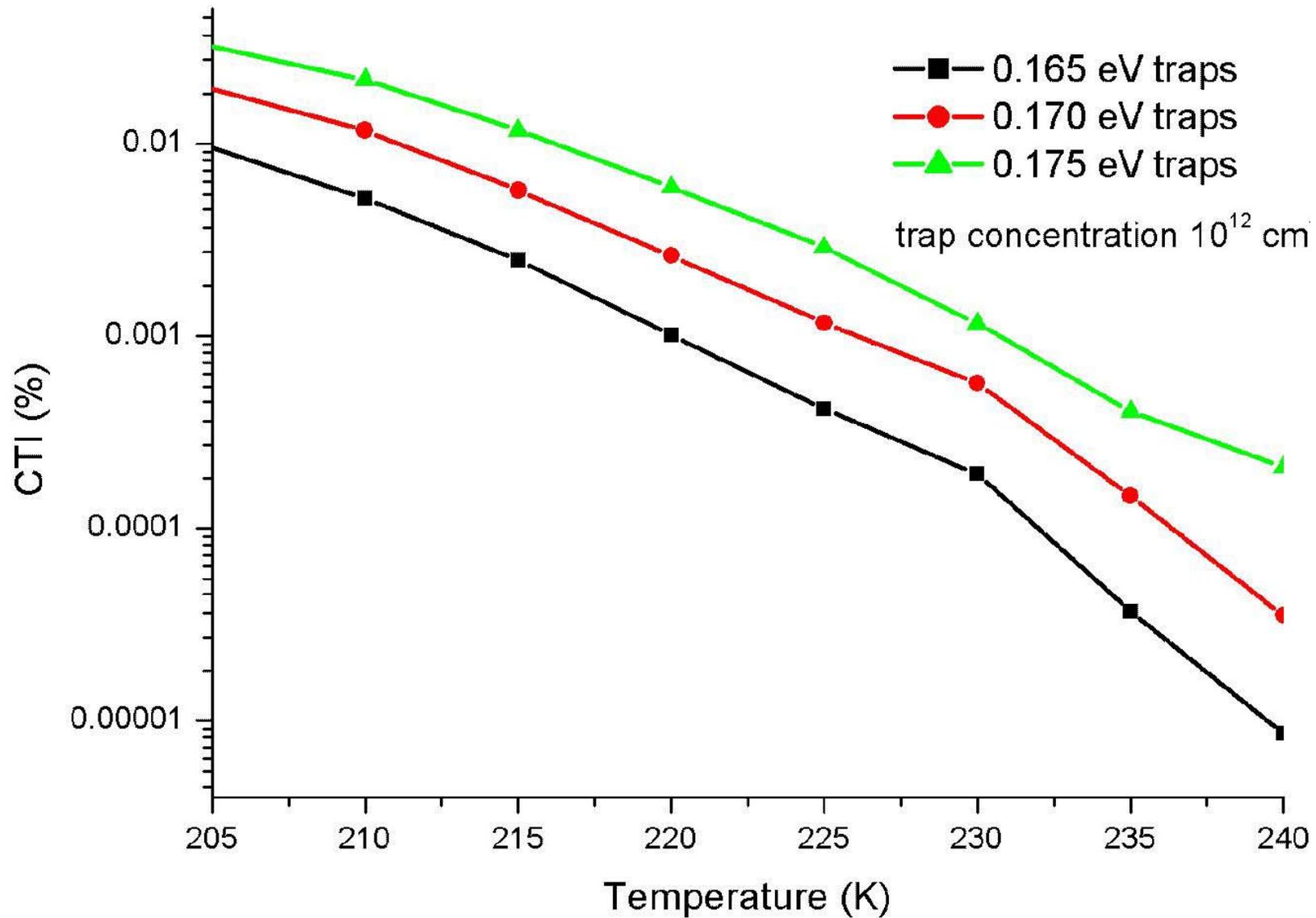
# CTI: Trap Concentrations



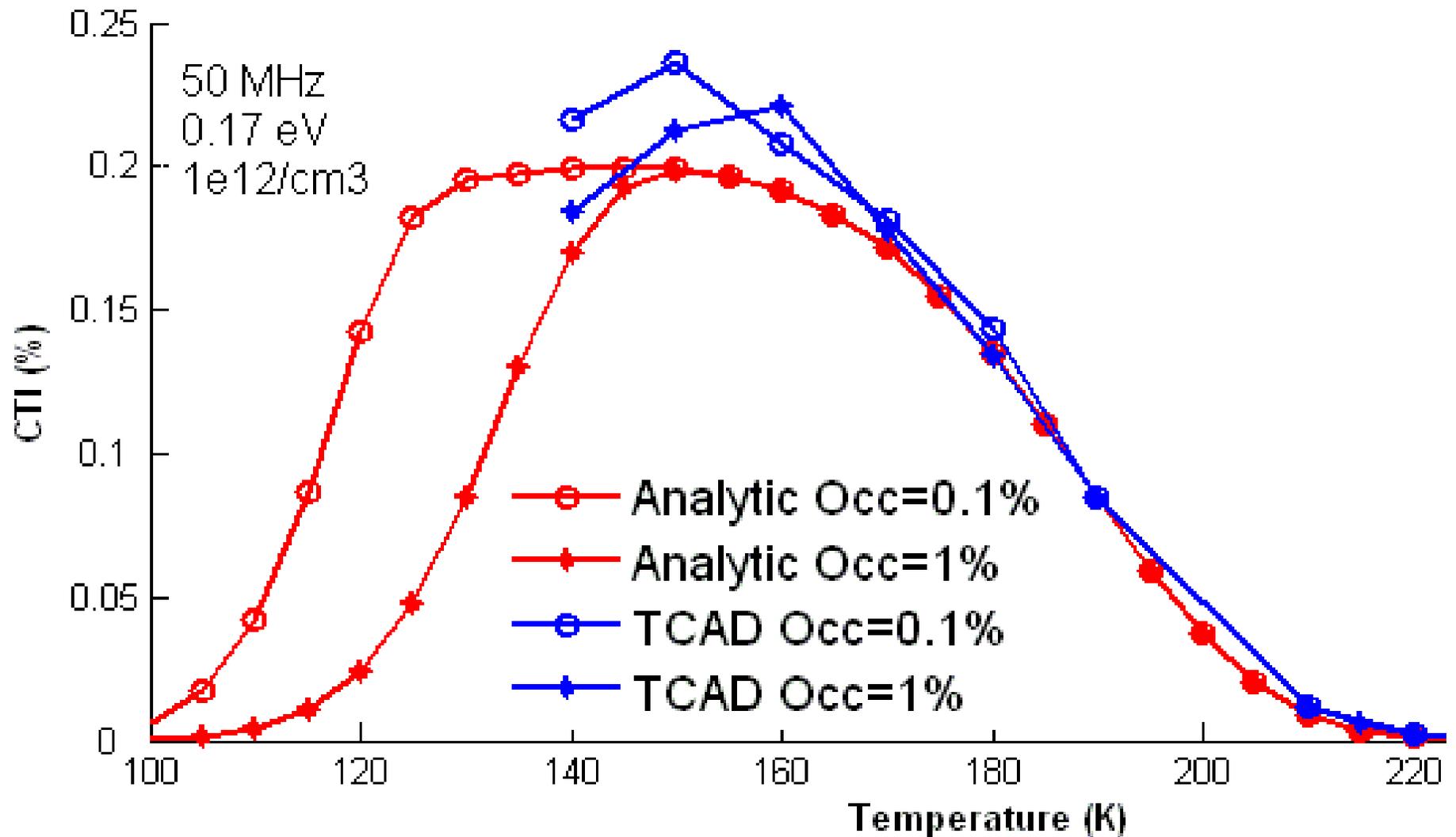
# CTI: Hit (Pixel) Occupancies and Frequencies



# CTI: Trap Energy Level Variations



# Analytic Model and Hit (Pixel) Occupancies



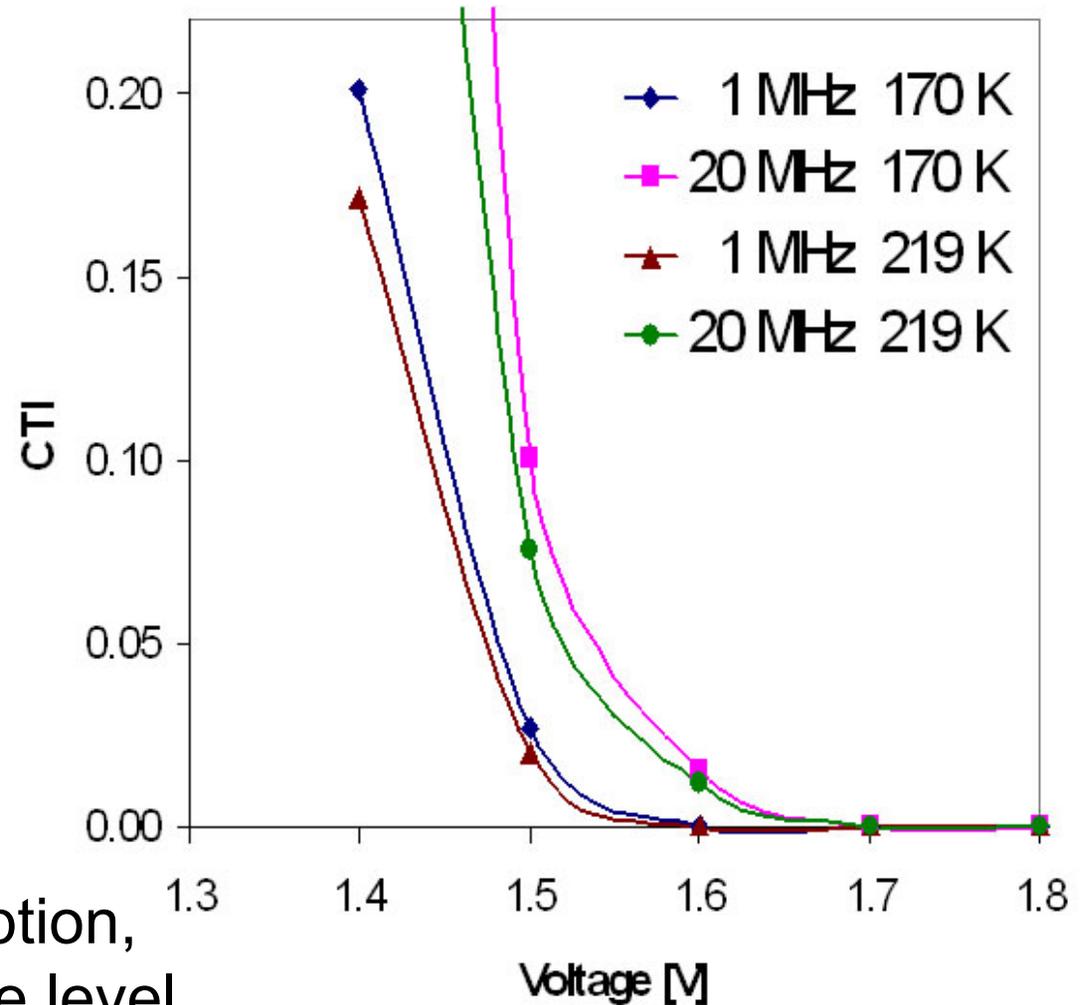
# CTI as a Function of Voltage Applied to Gates (Clock Voltage Induced CTI)

- Un-irradiated device: small CTI ( $< 10^{-6}$ ).
- decrease of clock voltage reduces transfer efficiency.



Find optimum clock voltage in order to

- reduce power consumption,
- keep CTI on acceptable level.



# Experimental Setup at Liverpool University



## Conclusions

- CCD with high-speed column-parallel readout simulated using the ISE-TCAD package with two trap energy levels.
- Optimal operation temperature about 230K to minimize CTI.
- CTI values determined for different
  - a) readout frequencies,
  - b) trap concentrations,
  - c) hit (pixel) occupancies,
  - d) variation of trap energy levels.
- Good agreement with expectations from analytical model.
- Comparison with data from irradiated CCDs essential.
- Test system in preparation to measure CTI for irradiated CCDs.
- High-speed CCD vertex detector development on track as vital part of a future ILC detector.